



CSP-50 Lead Free RoHS Profile

Total Mass of the Unit specified (g):	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.035	50 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	24.38077	706,392	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.01457	422	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.00905	262	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.00452	131	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.00452	131	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.03604	1,044	
		Metalization	BCB			0.05475	1,586	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	9.55993	276,983	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.40036	11,600	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.05	1,449	

Total mass (mg)	34.515
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